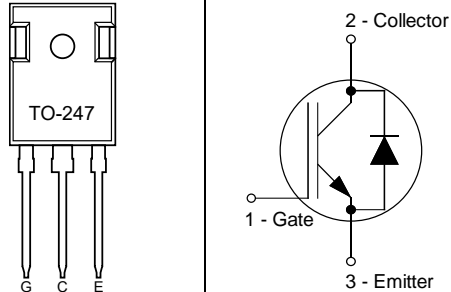


## 1200V 40A Trench and Field Stop IGBT

### Product Information

<b>Features</b> <ul style="list-style-type: none"> <li>◆ Advanced Field Stop technology</li> <li>◆ Low switching power loss</li> <li>◆ Low switching surge and noise</li> <li>◆ Low EMI</li> <li>◆ <math>T_{VJ}</math> 175°C</li> </ul>	<b>Package Marking and Ordering Information</b>	
	◆ Product Name:	KJG40N120P
<b>Applications</b> <ul style="list-style-type: none"> <li>◆ Industrial UPS</li> <li>◆ Welding machine</li> <li>◆ Solar converters</li> <li>◆ Energy storage</li> <li>◆ EV Charger</li> </ul>	◆ Marking:	KJG40N120P
	◆ Package:	TO-247
	◆ Quantity:	300 pcs
		

### Maximum Rated Values ( $T_{VJ}=25^{\circ}\text{C}$ , unless otherwise specified)

Parameter	Symbol	Value	Unit
Collector-Emitter Voltage	$V_{CES}$	1200	V
Gate-Emitter Voltage	$V_{GE}$	$\pm 20$	V
Transient Gate-Emitter Voltage ( $t_p \leq 10 \mu\text{s}$ , $D < 0.010$ )		$\pm 30$	
DC Collector Current, $T_C=25^{\circ}\text{C}$ (Limited by $T_{VJ}$ max)	$I_C$	65	A
DC Collector Current, $T_C=100^{\circ}\text{C}$ (Limited by $T_{VJ}$ max)		40	
Pulsed collector current ( $T_p$ limited by $T_{VJ}$ max) <sup>[1]</sup>	$I_{Cpuls}$	160	
Diode Forward Current, $T_C=25^{\circ}\text{C}$ ( $T_p$ limited by $T_{VJ}$ max)	$I_F$	65	
Diode Forward Current, $T_C=100^{\circ}\text{C}$ ( $T_p$ limited by $T_{VJ}$ max)		40	
Turn-Off Safe Operating Area $V_{CE} \leq 1200 \text{ V}$ , $T_{VJ} \leq 175^{\circ}\text{C}$ , $t_p = 1 \mu\text{s}$	-	160	
IGBT Max. Power Dissipation	$P_{D\_IGBT}$	420	W
FWD Max. Power Dissipation	$P_{D\_FRD}$	300	
Operating Junction Temperature	$T_{VJ}$	-40 to 175	°C
Storage Temperature	$T_{stg}$	-55 to 150	

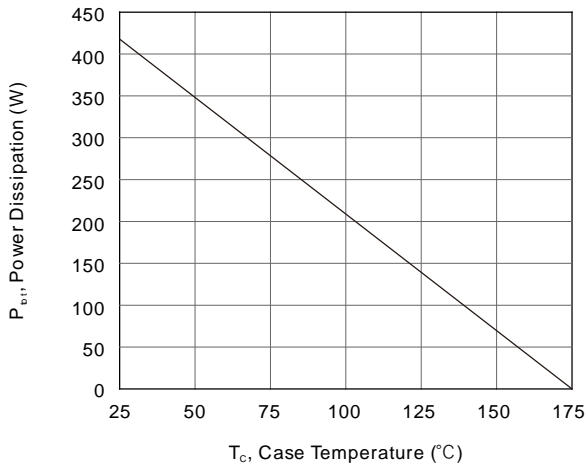
### Thermal Characteristics

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-Ambient	$R_{\theta JA}$	-	50	-	°C/W
IGBT Thermal Resistance, Junction-Case	$R_{\theta JC}$	-	0.35	-	
Diode Thermal Resistance, Junction-Case	$R_{\theta JCD}$	-	0.6	-	

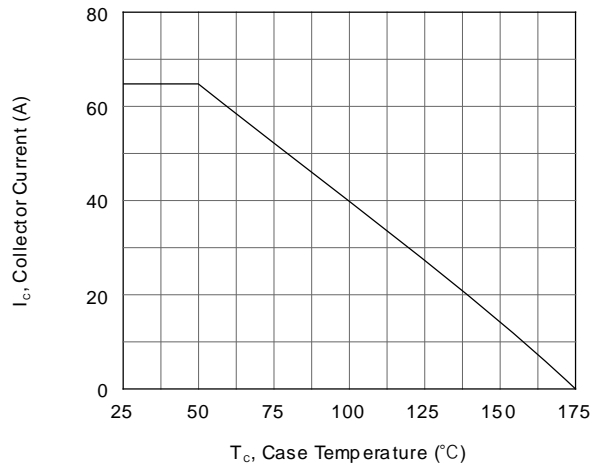
**Electrical Characteristics** ( $T_{VJ}=25^{\circ}\text{C}$ , unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Collector-Emitter Breakdown Voltage	$V_{(BR)CES}$	$V_{GE}=0\text{ V}$ , $I_C=0.25\text{ mA}$	1200	-	-	V
C-E Leakage Current	$I_{CES}$	$V_{CE}=1200\text{ V}$ , $V_{GE}=0\text{ V}$	-	-	200	$\mu\text{A}$
G-E Leakage Current	$I_{GES}$	$V_{CE}=0\text{ V}$ , $V_{GE}=\pm 20\text{ V}$	-	-	$\pm 200$	nA
G-E Threshold Voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}$ , $I_C=250\text{ }\mu\text{A}$	5.1	5.9	6.7	V
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$V_{GE}=15\text{ V}$ , $I_C=40\text{ A}$	-	1.75	2.20	V
		$T_{VJ}=25^{\circ}\text{C}$	-	2.40	-	
Diode Forward Voltage	$V_F$	$V_{GE}=0\text{ V}$ , $I_F=40\text{ A}$	-	1.7	3.0	-
		$T_{VJ}=175^{\circ}\text{C}$	-	1.5	-	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ies}$	$V_{CE}=25\text{ V}$ , $V_{GE}=0\text{ V}$ , $f=1\text{ MHz}$	-	9500	-	pF
Output Capacitance	$C_{oes}$		-	150	-	
Reverse Transfer Capacitance	$C_{res}$		-	86	-	
Gate Charge	$Q_G$	$V_{CC}=600\text{ V}$ , $I_C=40\text{ A}$ , $V_{GE}=15\text{ V}$	-	320	-	nC
<b>IGBT Switching Characteristics</b>						
Turn-on Delay Time	$t_{d(on)}$	$T_{VJ}=25^{\circ}\text{C}$ , $V_{CC}=600\text{ V}$ , $I_C=40\text{ A}$ , $V_{GE}=15\text{ V}$ , $R_G=10\text{ }\Omega$ , Inductive load	-	65	-	ns
Rise Time	$t_r$		-	110	-	
Turn-off Delay Time	$t_{d(off)}$		-	250	-	
Fall Time	$t_f$		-	75	-	
Turn-on Energy	$E_{on}$	Inductive load	-	2.1	-	mJ
Turn-off Energy	$E_{off}$		-	1.2	-	
Total Switching Energy	$E_{ts}$		-	3.3	-	
Turn-on Delay Time	$t_{d(on)}$	$T_{VJ}=175^{\circ}\text{C}$ , $V_{CC}=600\text{ V}$ , $I_C=40\text{ A}$ , $V_{GE}=15\text{ V}$ , $R_G=10\text{ }\Omega$ , Inductive load	-	60	-	ns
Rise Time	$t_r$		-	100	-	
Turn-off Delay Time	$t_{d(off)}$		-	360	-	
Fall Time	$t_f$		-	150	-	
Turn-on Energy	$E_{on}$	Inductive load	-	3.3	-	mJ
Turn-off Energy	$E_{off}$		-	2.3	-	
Total Switching Energy	$E_{ts}$		-	5.6	-	
<b>Diode Characteristics</b>						
Diode Reverse Recovery Time	$t_{rr}$	$T_j=25^{\circ}\text{C}$ , $V_{CC}=600\text{ V}$ , $I_F=40\text{ A}$ , $di_F/dt=300\text{ A}/\mu\text{s}$	-	270	-	ns
Diode Reverse Recovery Charge	$Q_{rr}$		-	2.8	-	$\mu\text{C}$
Diode Peak Reverse Recovery Current	$I_{rrm}$		-	19	-	A
Diode Reverse Recovery Time	$t_{rr}$	$T_j=175^{\circ}\text{C}$ , $V_{CC}=600\text{ V}$ , $I_F=40\text{ A}$ , $di_F/dt=300\text{ A}/\mu\text{s}$	-	440	-	ns
Diode Reverse Recovery Charge	$Q_{rr}$		-	8.5	-	$\mu\text{C}$
Diode Peak Reverse Recovery Current	$I_{rrm}$		-	89	-	A

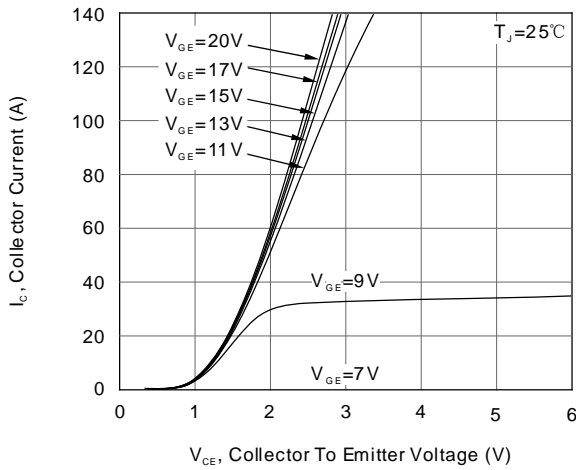
## Typical Electrical and Thermal Characteristics



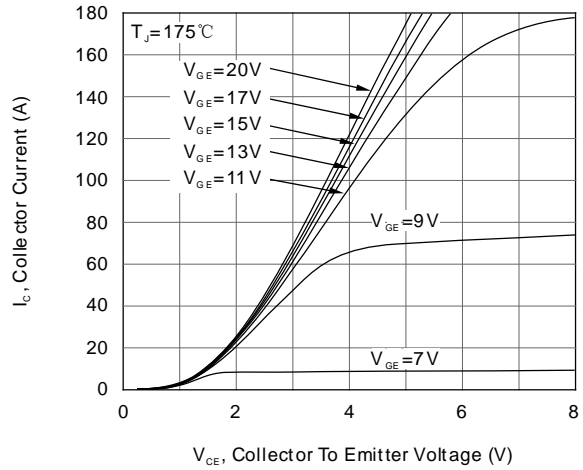
**Figure 1. Power dissipation vs. case temperature**  
( $T_{vj} \leq 175^\circ\text{C}$ )



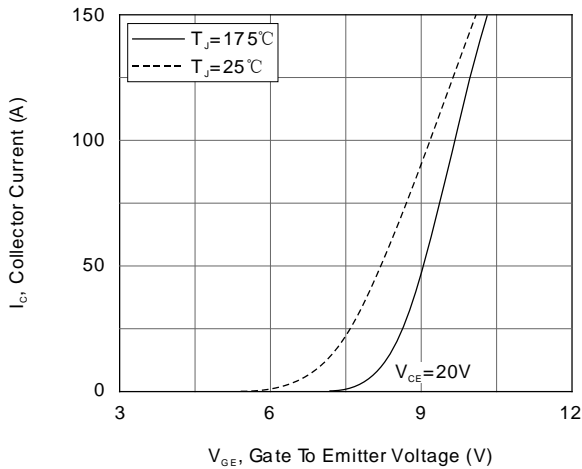
**Figure 2 Collector current vs. case temperature**  
( $V_{GE} \leq 15\text{V}$ ,  $T_{vj} \leq 175^\circ\text{C}$ )



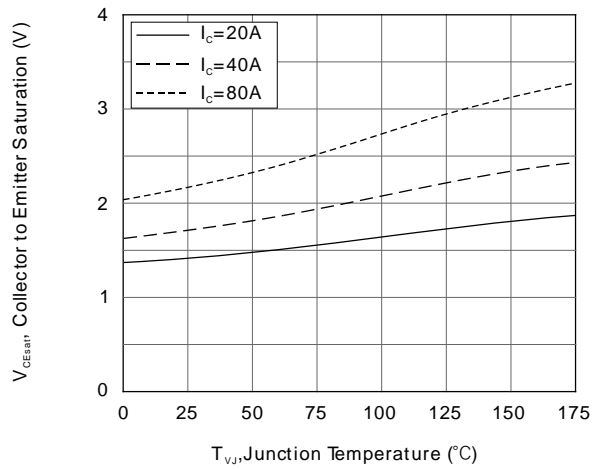
**Figure 3. Typical output characteristic**  
( $T_{vj} = 25^\circ\text{C}$ )



**Figure 4. Typical output characteristic**  
( $T_{vj} = 175^\circ\text{C}$ )

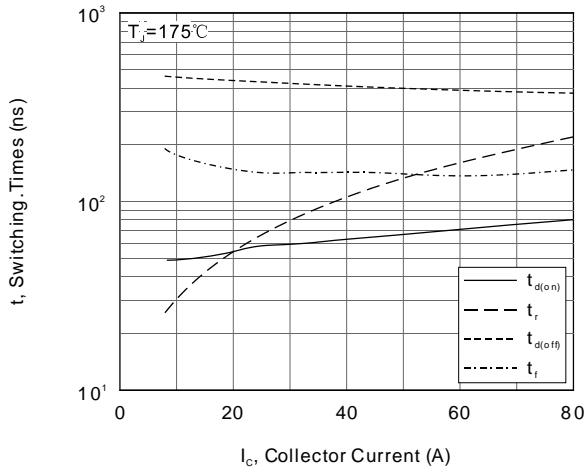


**Figure 5. Typical transfer characteristic**  
( $V_{CE} = 20\text{V}$ )

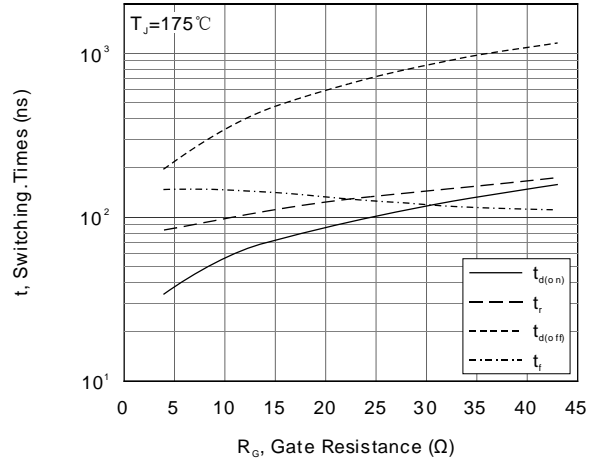


**Figure 6. Typical collector-emitter saturation voltage vs.  $T_{vj}$**   
( $V_{GE} = 20\text{V}$ )

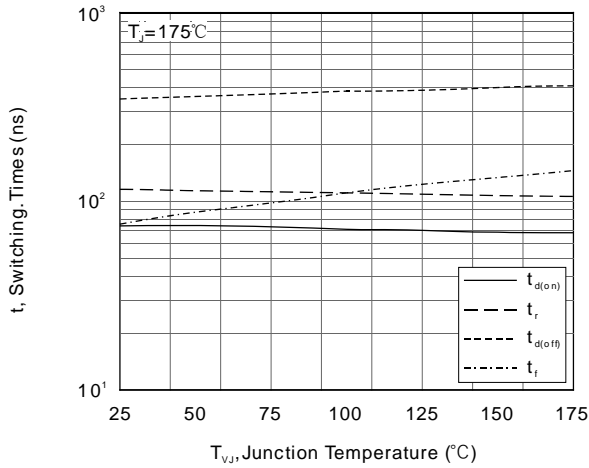
## Typical Electrical and Thermal Characteristics (cont.)



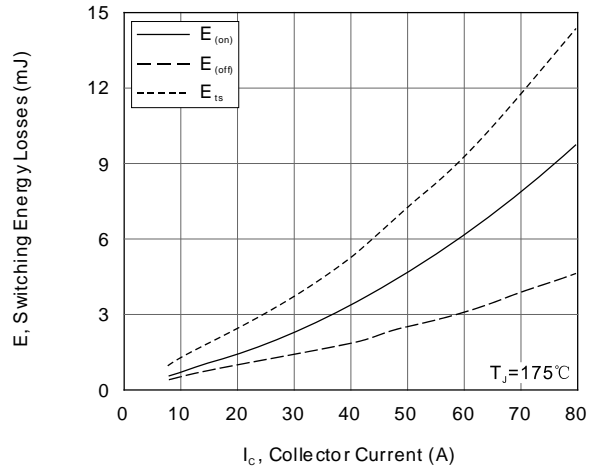
**Figure 7. Typical switching times vs. collector current**  
(Ind. load,  $T_{vj}=175^{\circ}\text{C}$ ,  $V_{ce}=600\text{V}$ ,  $V_{ge}=15/0\text{V}$ ,  $R_g=12\Omega$ )



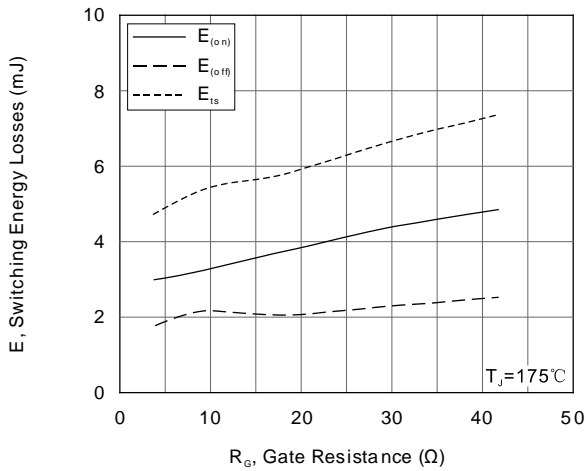
**Figure 8. Typical switching times vs. gate resistor**  
(Ind. Load,  $T_{vj}=175^{\circ}\text{C}$ ,  $V_{ce}=600\text{V}$ ,  $V_{ge}=15/0\text{V}$ ,  $I_c=40\text{A}$ )



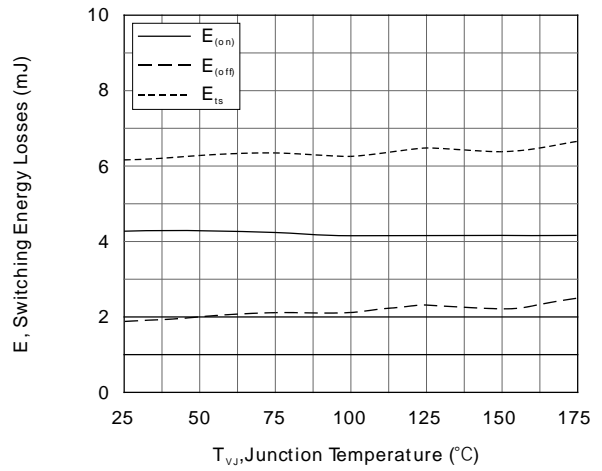
**Figure 9. Typical switching times vs.  $T_{vj}$**   
(Ind. Load,  $V_{ce}=600\text{V}$ ,  $V_{ge}=15/0\text{V}$ ,  $I_c=40\text{A}$ ,  $R_g=12\Omega$ )



**Figure 10. Typical switching energy losses vs. collector current**  
(Ind. load,  $T_{vj}=175^{\circ}\text{C}$ ,  $V_{ce}=600\text{V}$ ,  $V_{ge}=15/0\text{V}$ ,  $R_g=12\Omega$ )

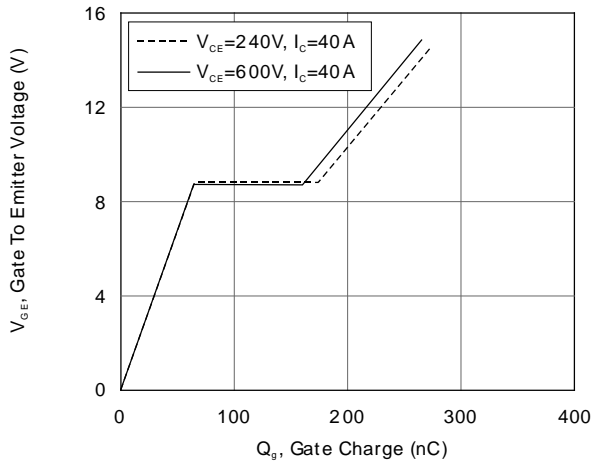


**Figure 11. Typical switching energy losses vs. gate resistor**  
(Ind. load,  $T_{vj}=175^{\circ}\text{C}$ ,  $V_{ce}=600\text{V}$ ,  $V_{ge}=15/0\text{V}$ ,  $I_c=40\text{A}$ )

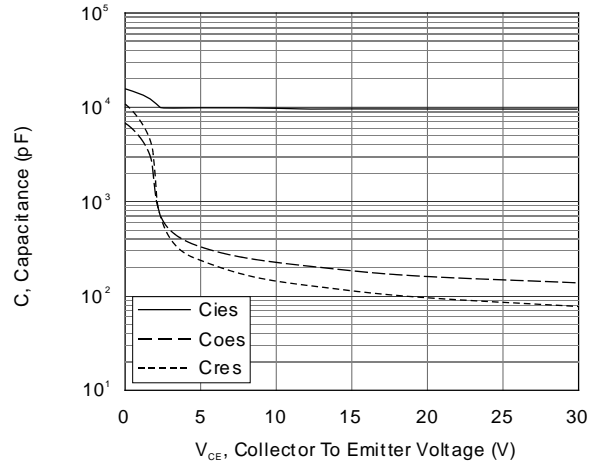


**Figure 12. Typical switching energy losses vs.  $T_{vj}$**   
(Ind load,  $V_{ce}=600\text{V}$ ,  $V_{ge}=15/0\text{V}$ ,  $I_c=40\text{A}$ ,  $R_g=12\Omega$ )

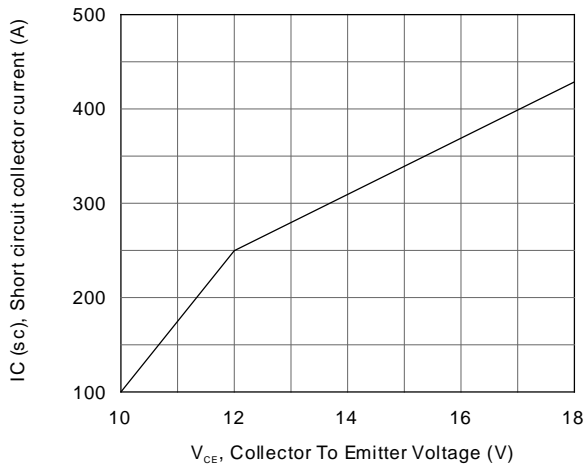
## Typical Electrical and Thermal Characteristics (cont.)



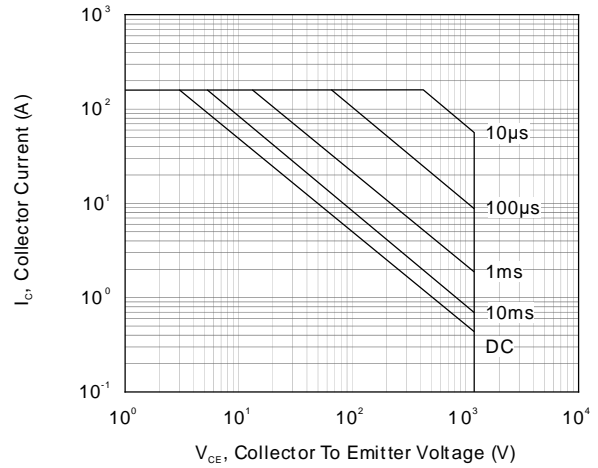
**Figure 13. Typical gate charge**  
( $I_C=40A$ )



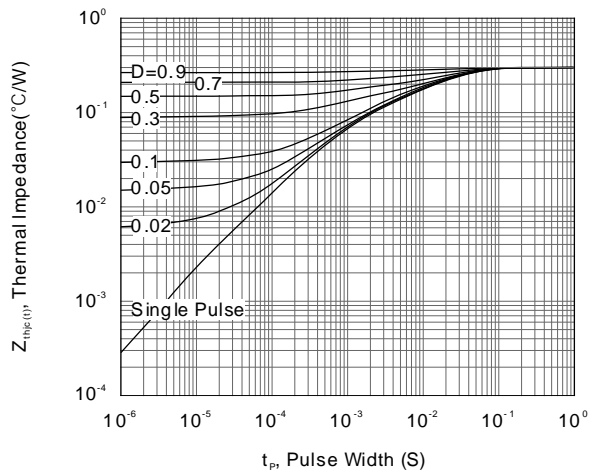
**Figure 14. Typical capacitance vs. collector-emitter voltage**  
( $V_{GE}=0V, f=1MHz$ )



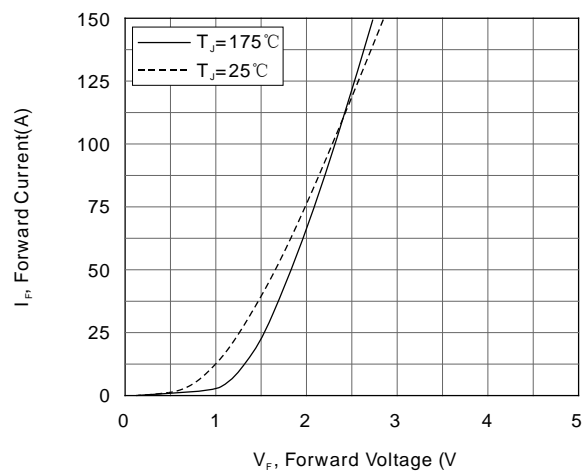
**Figure 15. Typical short circuit collector current vs. gate-emitter voltage**  
( $V_{CE} \leq 600V$  start at  $T_J=25^\circ C$ )



**Figure 16. Forward bias safe operating area**  
( $D=0, T_C=25^\circ C, T_{VJ} \leq 175^\circ C; V_{GE}=15V$ )



**Figure 17. IGBT transient thermal impedance**  
( $D=tp/T$ )



**Figure 18. Typical diode forward current vs. forward voltage**

## Typical Electrical and Thermal Characteristics (cont.)

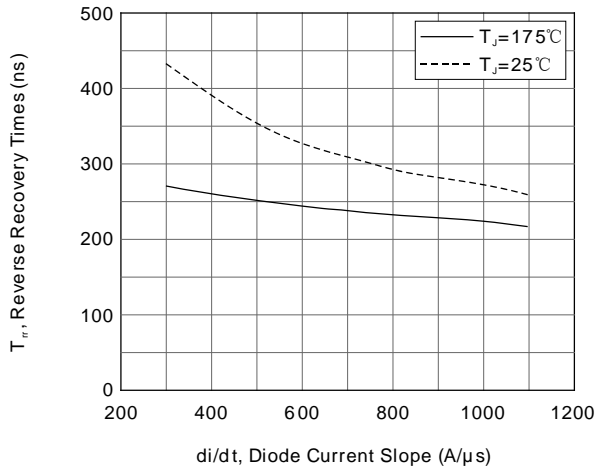


Figure 19. Typical reverse recovery time vs. diode current slope ( $V_R=600V$ )

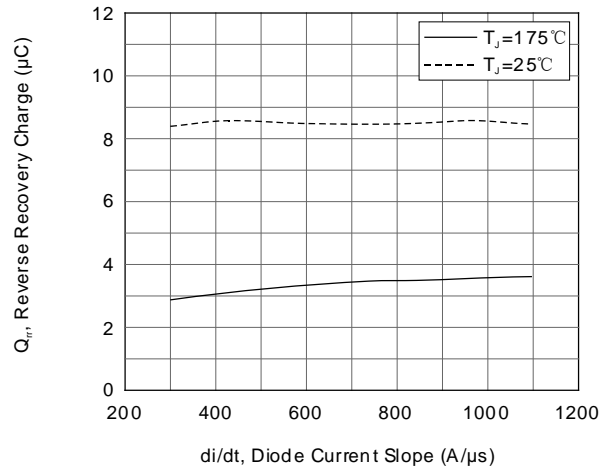


Figure 20. Typical reverse recovery charge vs. diode current slope ( $V_R=600V$ )

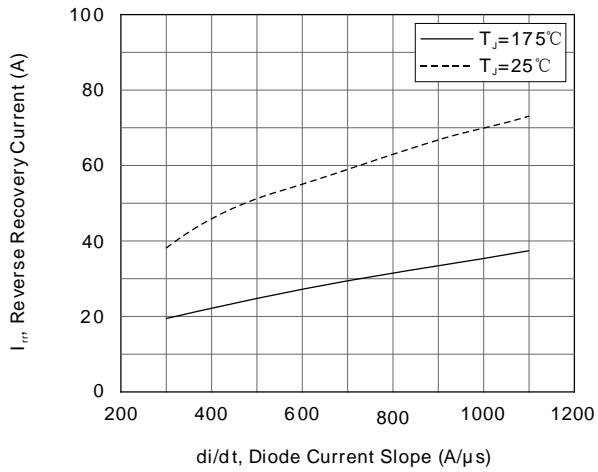
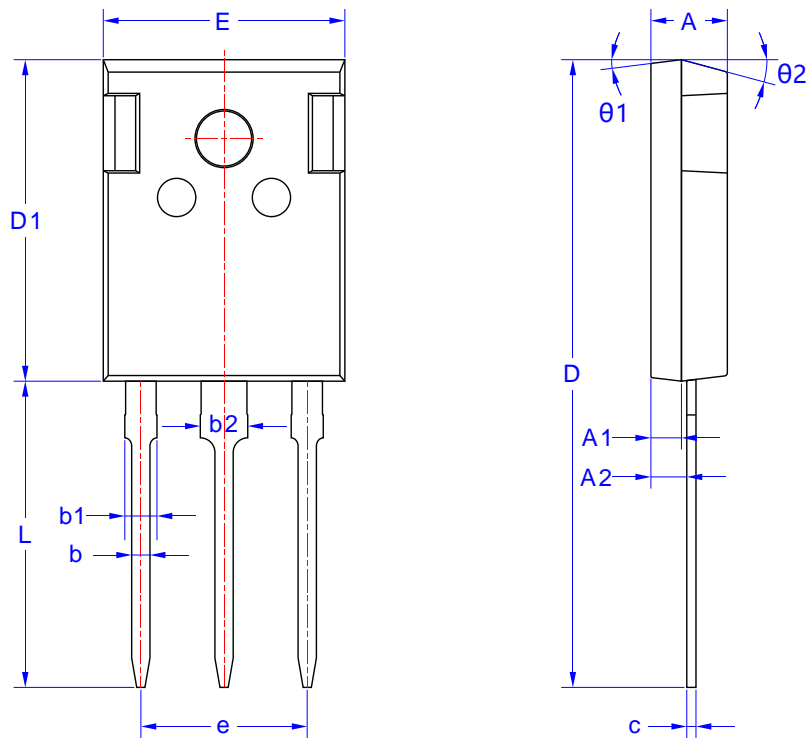


Figure 21. Typical reverse recovery current vs. diode current slope ( $V_R=600V$ )

## Package Mechanical Data

TO-247 Package



Symbol	Dimensions in Millimeters		
	MIN.	NOM.	MAX.
A	4.90	5.00	5.10
A1	1.90	2.00	2.10
A2	2.25	2.35	2.45
b		1.20	
b1		2.10	
b2		3.10	
c		0.60	
D	40.00	41.00	42.00
D1	20.80	21.00	21.20
E	15.60	15.80	16.00
e		10.88	
L	19.80	20.00	20.20
$\theta 1$		7°	
$\theta 2$		15°	